

16384 x 1 BIT DYNAMIC MOS RANDOM ACCESS MEMORY

DESCRIPTION The μ PD2118 is a single +5V power supply, 16384 word by 1 bit Dynamic MOS RAM. The μ PD2118 achieves high speed with low power dissipation by the use of single transistor dynamic storage cell design and advanced dynamic circuitry. This circuit design results in the minimizing of current transients typical of dynamic RAMS. This in turn results in high noise immunity of the μ PD2118 in a system environment. By using a multiplexing technique, the μ PD2118 can be packaged in an industry standard 16-Pin Dip utilizing 7 address input pins for the 14 address bits required. The two 7 bit address words are referred to as the ROW and COLUMN address. Two TTL clocks, ROW address strobe (\overline{RAS}) and COLUMN address strobe (\overline{CAS}) latch these two words into the μ PD2118. Non-critical timing requirements for \overline{RAS} and \overline{CAS} permit high systems performance without placing difficult constraints upon the multiplexing control circuitry.

The μ PD2118 has a three-state output controlled by \overline{CAS} , independent of \overline{RAS} . Following a valid read or read-modify-write cycle, data will be held in the output by holding \overline{CAS} low. Returning \overline{CAS} to a high state will result in the data out pin reverting to the high impedance mode. Use of this \overline{CAS} controlled output means that the μ PD2118 can perform hidden refresh by holding \overline{CAS} low to maintain latch data output while using \overline{RAS} to execute \overline{RAS} -only-refresh cycles.

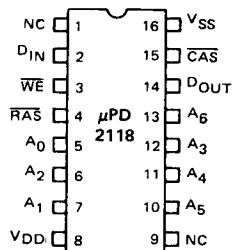
The use of single transistor storage cell circuitry requires that data be periodically refreshed. Refreshing can be accomplished by performing \overline{RAS} -only-refresh cycles, hidden refresh cycles or normal read or write cycles on each of the 128 address combinations of A0 through A6 during a 2 ms period. The write cycle will refresh stored data on all bits of the selected row, except that the bit which is addressed will be modified to reflect the data input.

FEATURES

- Single +5V Supply, $\pm 10\%$ Tolerance
- Low Power: 138 mW Max Operating
16 mW Max Standby
- Low VDD Current Transients
- All Inputs, Including Clocks, TTL Compatible
- Non-Latched Output is Three-State
- \overline{RAS} -Only-Refresh
- 128 Refresh Cycles Required
- Page Mode Capability
- \overline{CAS} Controlled Output Allows Hidden Refresh

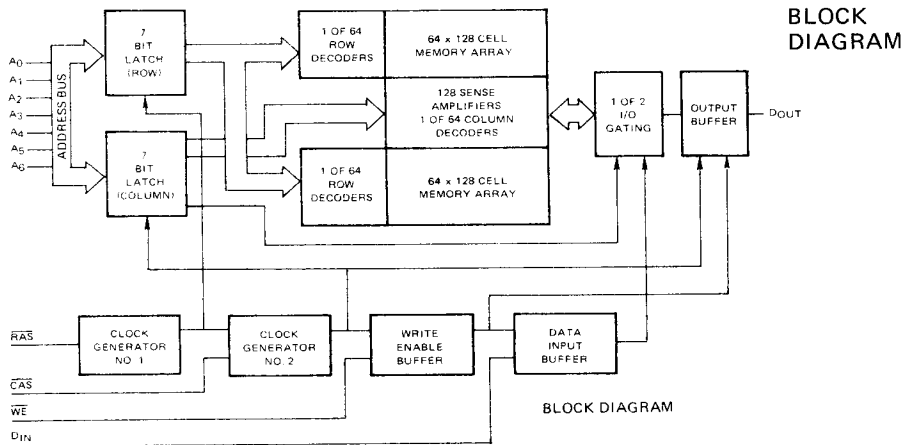
P/N	ACCESS TIME	R/W CYCLE	RMW CYCLE
μ PD2118	150 ns	320 ns	410 ns
μ PD2118-2	120 ns	270 ns	345 ns
μ PD2118-3	100 ns	235 ns	295 ns

PIN CONFIGURATION



PIN NAMES

A0-A6	ADDRESS INPUTS
\overline{CAS}	COLUMN ADDRESS STROBE
DIN	DATA IN
DOUT	DATA OUT
WE	WRITE ENABLE
\overline{RAS}	ROW ADDRESS STROBE
VDD	POWER (+5V)
VSS	GROUND



Ambient Temperature Under Bias	-10°C to +80°C
Storage Temperature	-65°C to +150°C
Voltage On Any Pin Relative to VSS	-2.0 to +7.5V
Data Out Current	50 mA
Power Dissipation	1.0W

**ABSOLUTE MAXIMUM
RATINGS***

*COMMENT: Stress above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or at any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS
READ, WRITE, AND
READ MODIFY WRITE
CYCLES ①

T_a = 0°C to 70°C, V_{DD} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted.

PARAMETER		SYMBOL	LIMITS			TEST CONDITIONS	NOTES
			MIN	MAX	UNIT		
Input Load Current		I _{LI}		10	μA	V _{IN} = V _{SS} to V _{DD}	
Output Leakage Current for High Impedance State		I _{LO}		10	μA	Chip Deselected $\overline{\text{CAS}}$ at V _{IH} , V _{OUT} = 0 to 5.5V	
V _{DD} Supply Current (Standby)		I _{DD1}		3	mA	$\overline{\text{CAS}}$ and $\overline{\text{RAS}}$ at V _{IH}	
V _{DD} Supply Current (Operating)	μPD2118-3	I _{DD2}		25	mA	TRC = TRC Min	②
	μPD2118-2	I _{DD2}		22	mA		
	μPD2118-0	I _{DD2}		22	mA		
V _{DD} Supply Current (RAS-Only Cycle)	μPD2118-3	I _{DD3}		20	mA	TRC = TRC Min	②
	μPD2118-2	I _{DD3}		18	mA		
	μPD2118-0	I _{DD3}		18	mA		
V _{DD} Supply Current Page Mode, Maximum t _{PC} Minimum t _{CAS}	μPD2118-3	I _{DD4}		20	mA		②
	μPD2118-2	I _{DD4}		17	mA		
	μPD2118-0	I _{DD4}		15	mA		
V _{DD} Supply Current (Standby, Output Enabled)		I _{DD5}		4	mA	$\overline{\text{CAS}}$ at V _{IL} , $\overline{\text{RAS}}$ at V _{IH}	②
Input Low Voltage		V _{IL}	-2.0	0.8	V		
Input High Voltage		V _{IH}	2.4	7.0	V		
Output Low Voltage		V _{OL}		0.4	V	I _{OL} = 4.2 mA	
Output High Voltage		V _{OH}	2.4			I _{OH} = -5 mA	

- Notes: ① All voltages referenced to V_{SS}
② I_{DD} is dependent on output loading when the device output is selected. Specified I_{DD} Max is measured with the output open.

CAPACITANCE ①

T_a = 25°C, V_{DD} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted.

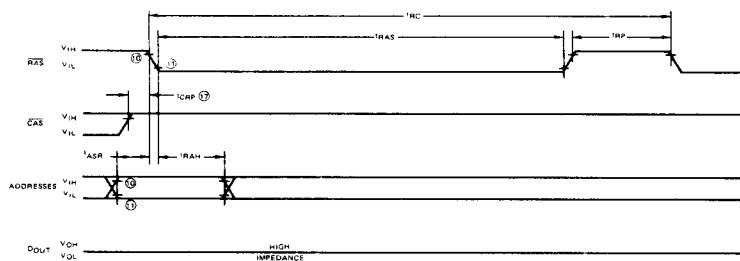
SYMBOL	PARAMETER	TYP	MAX	UNIT
CI1	Address, Data In	3	5	pF
CI2	RAS, WE	4	7	pF
CI3	CAS	6	10	pF
CO	Data Out	4	7	pF

- NOTES: ① Capacitance measured with Boonton meter or effective capacitance calculated from the Equation C = IΔT/ΔV with ΔV equal to 3V and power supplies at nominal levels.

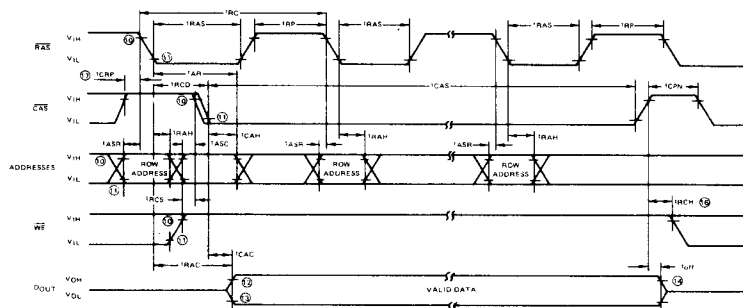
READ, WRITE, READ-MODIFY-WRITE AND REFRESH CYCLES

SYMBOL	PARAMETER	μPD2118-3		μPD2118-2		μPD2118-0		UNIT	NOTES
		MIN	MAX	MIN	MAX	MIN	MAX		
t _{RAC}	Access Time From RAS		100		120		150	ns	④ ⑤
t _{CAC}	Access Time From CAS		50		65		80	ns	④ ⑤ ⑥
t _{REF}	Time Between Refresh		2		2		2	ms	
t _{RP}	RAS Precharge Time	110		120		135		ns	
t _{CPN}	CAS Precharge Time (non-page-mode cycles)	50		55		70		ns	
t _{CRP}	CAS to RAS Precharge Time	0		0		0		ns	
t _{RCD}	RAS to CAS Delay Time	20	50	20	55	25	70	ns	⑦
t _{RS}	RAS Hold Time	65		85		105		ns	
t _{CS}	CAS Hold Time	110		135		165		ns	
t _{ASR}	Row Address Set-Up Time	0		0		0		ns	
t _{RAH}	Row Address Hold Time	10		10		15		ns	
t _{ASC}	Column Address Set-Up Time	0		0		0		ns	
t _{CAH}	Column Address Hold Time	15		15		20		ns	
t _{AR}	Column Address Hold Time, to RAS	65		70		90		ns	
t _T	Transition Time (Rise and Fall)	3	50	3	50	3	50	ns	⑧
t _{OFF}	Output Buffer Turn Off Delay	0	45	0	50	0	60	ns	
READ AND REFRESH CYCLES									
t _{RC}	Random Read Cycle Time	235		270		320		ns	
t _{RAS}	RAS Pulse Width	115	10,000	140	10,000	175	10,000	ns	
t _{CAS}	CAS Pulse Width	60	10,000	80	10,000	95	10,000	ns	
t _{RCS}	Read Command Set-Up Time	0		0		0		ns	
t _{RCH}	Read Command Hold Time	0		0		0		ns	
WRITE CYCLE									
t _{RC}	Random Write Cycle Time	235		270		320		ns	
t _{RAS}	RAS Pulse Width	115	10,000	140	10,000	175	10,000	ns	
t _{CAS}	CAS Pulse Width	60	10,000	80	10,000	95	10,000	ns	
t _{WCS}	Write Command Set-Up Time	0		0		0		ns	⑨
t _{WCH}	Write Command Hold Time	30		35		45		ns	
t _{WCR}	Write Command Hold Time, to RAS	80		90		115		ns	
t _{WP}	Write Command Pulse Width	35		40		50		ns	
t _{RWL}	Write Command to RAS Lead Time	70		90		110		ns	
t _{CWL}	Write Command to CAS Lead Time	65		85		100		ns	
t _{DS}	Data-In Set-Up Time	0		0		0		ns	
t _{DH}	Data-In Hold Time	30		35		45		ns	
t _{DHR}	Data-In Hold Time, to RAS	80		90		115		ns	
READ-MODIFY-WRITE CYCLE									
t _{RWC}	Read-Modify-Write Cycle Time	295		345		410		ns	
t _{RRW}	RMW Cycle RAS Pulse Width	175	10,000	215	10,000	265	10,000	ns	
t _{CRW}	RMW Cycle CAS Pulse Width	120	10,000	155	10,000	185	10,000	ns	
t _{RWD}	RAS to WE Delay	100		120		150		ns	⑨
t _{CWD}	CAS to WE Delay	50		65		80		ns	⑨
PAGE MODE CYCLE									
t _{PC}	Page Mode Read or Write Cycle	130		160		190		ns	
t _{PCM}	Page Mode Read-Modify-Write	190		235		280		ns	
t _{CP}	CAS Precharge Time, Page Cycle	60		70		85		ns	
t _{RP}	RAS Pulse Width, Page Mode	125	10,000	150	10,000	175	10,000	ns	
t _{CAS}	CAS Pulse Width	60	10,000	80	10,000	95	10,000	ns	

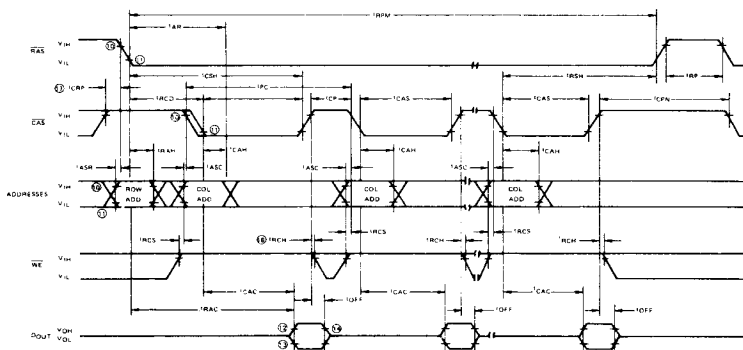
*NOTES: See page 7.



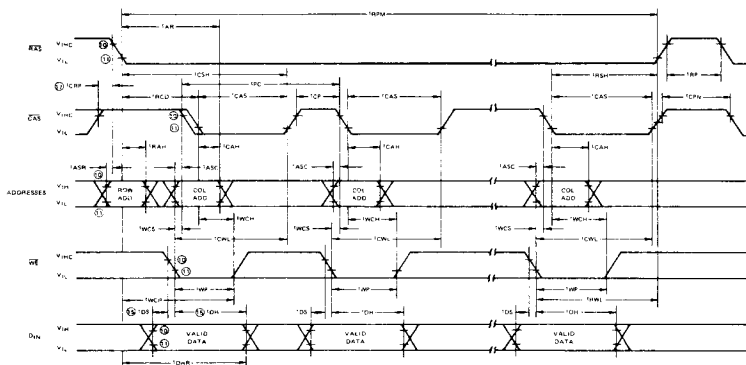
HIDDEN REFRESH CYCLE



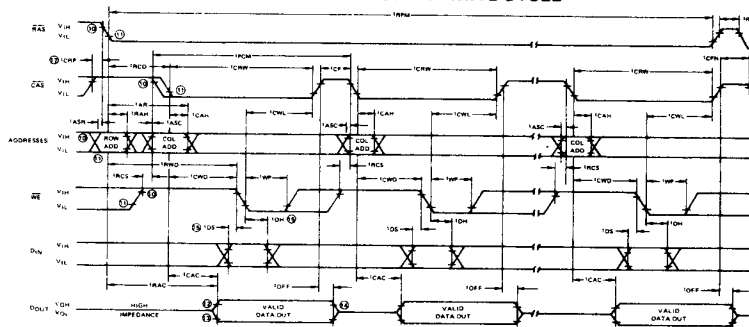
PAGE MODE READ CYCLE



PAGE MODE WRITE CYCLE



PAGE MODE READ-MODIFY-WRITE CYCLE



- Notes:
- ① All voltages referenced to V_{SS}.
- ② Eight cycles are required after power-up or prolonged periods greater than 2 ms of $\overline{\text{RAS}}$ inactivity before proper device operation is achieved. Any 8 cycles which perform refresh are adequate for this purpose.
- ③ AC Characteristics assume $t_T = 5$ ns.
- ④ Assume that $t_{\text{RCD}} \leq t_{\text{RCD}}(\text{max})$. If t_{RCD} is greater than $t_{\text{RCD}}(\text{max})$, then t_{RAC} will increase by the amount that t_{RCD} exceeds $t_{\text{RCD}}(\text{max})$.
- ⑤ Load = 2 TTL loads and 100pF.
- ⑥ Assumes $t_{\text{RCD}} \geq t_{\text{RCD}}(\text{max})$.
- ⑦ $t_{\text{RCD}}(\text{max})$ is specified as a reference point only: if t_{RCD} is less than $t_{\text{RCD}}(\text{max})$ access time is t_{RAC} . If t_{RCD} is greater than $t_{\text{RCD}}(\text{max})$ access time is $t_{\text{RCD}} + t_{\text{CAC}}$.
- ⑧ t_{RAC} is measured between $V_{\text{IH}}(\text{min})$ and $V_{\text{IL}}(\text{max})$.
- ⑨ $t_{\text{WC}} \geq t_{\text{WC}}(\text{min})$ and $t_{\text{WD}} \geq t_{\text{WD}}(\text{min})$ are specified as reference points only. If $t_{\text{WC}} \geq t_{\text{WC}}(\text{min})$ the cycle is an early write cycle and the data out pin will remain high impedance throughout the entire cycle. If $t_{\text{WC}} < t_{\text{WC}}(\text{min})$ and $t_{\text{WD}} \geq t_{\text{WD}}(\text{min})$, the cycle is a read-modify-write cycle and the data out will contain the data read from the selected address. If neither of the above conditions is satisfied, the condition of the data out is indeterminate.
- ⑩ $V_{\text{IH}}(\text{min})$ and $V_{\text{IL}}(\text{max})$ are reference levels for measuring timing of input signals.
- ⑪ $V_{\text{OH}}(\text{min})$ and $V_{\text{OL}}(\text{max})$ are reference levels for measuring timing of D_{OUT} .
- ⑫ t_{QFF} is measured to $I_{\text{OUT}} < I_{\text{ILO}}$.
- ⑬ t_{DS} and t_{DH} are referenced to $\overline{\text{CAS}}$ or $\overline{\text{WE}}$, whichever occurs last.
- ⑭ t_{RCH} is referenced to the trailing edge of $\overline{\text{CAS}}$ or $\overline{\text{RAS}}$, whichever occurs first.
- ⑮ t_{CRP} requirements is only applicable for $\overline{\text{RAS}}/\overline{\text{CAS}}$ cycles preceded by a $\overline{\text{CAS}}$ -only cycle (i.e., for systems where CAS has not been decoded with RAS).

A Read cycle is performed by maintaining Write Enable (\overline{WE}) high during a $\overline{RAS}/\overline{CAS}$ operation. The output pin of a selected device will remain in a high impedance state until valid data appears at the output at access time. Device access time, t_{ACC} , is the longer of the two calculated intervals $t_{ACC} = t_{RAC}$ or $t_{ACC} = t_{RCD} + t_{CAC}$.

Access time from $\overline{\text{RAS}}$, t_{RAC} , and access time from $\overline{\text{CAS}}$, t_{CAC} , are device parameters. Row to column address strobe delay time, t_{RCD} , are system dependent timing parameters. For example, substituting the device parameters of the $\mu\text{PD}2118\text{-}3$ yields $t_{\text{ACC}} = t_{\text{RAC}} = 100 \text{ nsec}$ for $20 \text{ nsec} \leq t_{\text{RCD}} \leq 50 \text{ nsec}$, but $t_{\text{ACC}} = t_{\text{RCD}} + t_{\text{CAC}} = t_{\text{RCD}} + 50$ for $t_{\text{RCD}} > 50 \text{ nsec}$.

Note that if $20 \text{ nsec} \leq t_{\text{RCD}} \leq 50 \text{ nsec}$ device access time is determined by the first equation and is equal to t_{RAC} . If $t_{\text{RCD}} > 50 \text{ nsec}$, access time is determined by the second equation. This 30 nsec interval (shown in the t_{RCD} inequality in the first equation) in which the falling edge of $\overline{\text{CAS}}$ can occur without affecting access time is provided to allow for system timing skew in the generation of $\overline{\text{CAS}}$.

μ PD2118

Each of the 128 rows of the μPD2118 must be refreshed every 2 milliseconds to maintain data. Any memory cycle (read, write, or $\overline{\text{RAS}}$ only) refreshes the selected row as defined by the low order ($\overline{\text{RAS}}$) addresses. Any Write cycle, of course, may change the state of the selected cell. Using a Read, Write, or Read-Modify-Write cycle for refresh is not recommended for systems which utilize "wire-OR" outputs since output bus contention will occur.

A $\overline{\text{RAS}}$ -only refresh cycle is the recommended technique for most applications to provide for data retention. A $\overline{\text{RAS}}$ -only refresh cycle maintains the DOUT in the high impedance state with a typical power reduction of 20% over a Read or Write cycle.

REFRESH CYCLES

$\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ have minimum pulse widths as defined by t_{RAS} and t_{CAS} respectively. These minimum pulse widths must be maintained for proper device operation and data integrity. A cycle once begun by bringing $\overline{\text{RAS}}$ and/or $\overline{\text{CAS}}$ low must not be ended or aborted prior to fulfilling the minimum clock signal pulse width(s). A new cycle can not begin until the minimum precharge time, t_{RP} , has been met.

$\overline{\text{RAS}}/\overline{\text{CAS}}$ TIMING

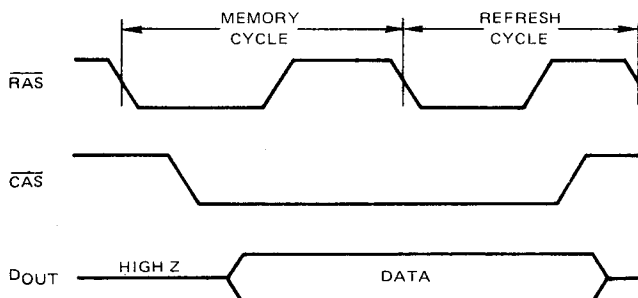
Data Output (DOUT), which has three-state capability, is controlled by $\overline{\text{CAS}}$. During $\overline{\text{CAS}}$ high state ($\overline{\text{CAS}}$ at V_{IH}) the output is in the high impedance state. The following table summarizes the DOUT state for various types of cycles.

DATA OUTPUT OPERATION

Type of Cycle	DOUT State
Read Cycle	Data From Addressed Memory Cell
Early Write Cycle	HI-Z
$\overline{\text{RAS}}$ -Only Refresh Cycle	HI-Z
$\overline{\text{CAS}}$ -Only Cycle	HI-Z
Read/Modify/Write Cycle	Data From Addressed Memory Cell
Delayed Write Cycle	Indeterminate

HIDDEN REFRESH

A feature of the μPD2118 is that refresh cycles may be performed while maintaining valid data at the output pin. This feature is referred to as Hidden Refresh. Hidden Refresh is performed by holding $\overline{\text{CAS}}$ at V_{IL} and taking $\overline{\text{RAS}}$ high and after a specified precharge period (t_{RP}) executing a " $\overline{\text{RAS}}$ -Only" refresh cycle, but with $\overline{\text{CAS}}$ held low (see Figure below).

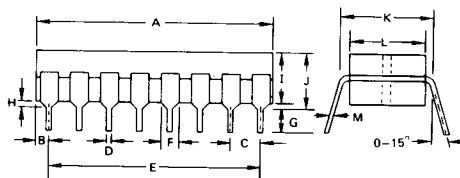


This feature allows a refresh cycle to be "hidden" among data cycles without affecting the data availability.

POWER ON The μPD2118 requires no power on sequence. After the application of the V_{DD} supply, or after extended periods of bias (greater than 2 ms) without clocks, the device must perform a minimum of eight (8) initialization cycles (any combination of cycles containing a $\overline{\text{RAC}}$ clock such as $\overline{\text{RAS}}$ -only refresh) prior to normal operation.

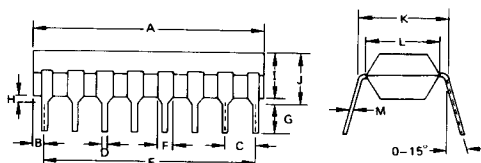
The V_{DD} current (I_{DD}) requirement of the μPD2118 during power on is, however, dependent upon the input levels of $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$. If the input levels of these clocks are at V_{IH} or V_{DD}, whichever is lower, the I_{DD} requirement per device is I_{DD1} (I_{DD} standby). If the input levels for the two clocks are lower than V_{IH} or V_{DD}, the I_{DD} requirement will be greater than I_{DD1}. For large systems, this current requirement for I_{DD} could be substantially more than that for which the system has been designed. A system which has been designed assuming the majority of devices to be operating in the refresh/standby mode may produce sufficient I_{DD} loading such that the power supply might current limit. To assure that the system will not experience such loading during power on, a pullup resistor for each clock input to V_{DD} to maintain the non-selected current level (I_{DD1}) for the power supply is recommended.

PACKAGE OUTLINE
μPD2118D



Cerdip		
ITEM	MILLIMETERS	INCHES
A	19.3 MAX	0.759 MAX
B	1.06	0.042
C	2.54	0.10
D	0.46 ± 0.10	0.018 ± 0.004
E	17.78	0.70
F	1.5	0.059
G	2.54 MIN	0.10 MIN
H	0.5 MIN	0.019 MIN
I	4.58 MAX	0.181 MAX
J	5.08 MAX	0.20 MAX
K	7.62	0.30
L	6.4	0.25
M	0.75 ± 0.10 -0.05	0.0098 ± 0.0039 -0.0019

μPD2118C



Plastic		
ITEM	MILLIMETERS	INCHES
A	19.4 MAX	0.76 MAX
B	0.81	0.03
C	2.54	0.10
D	0.5	0.02
E	17.78	0.70
F	1.3	0.051
G	2.54 MIN	0.10 MIN
H	0.5 MIN	0.02 MIN
I	4.05 MAX	0.16 MAX
J	4.55 MAX	0.18 MAX
K	7.62	0.30
L	6.4	0.25
M	0.75 ± 0.10 -0.05	0.03 ± 0.004 -0.002

2118DS-12-80-CAT